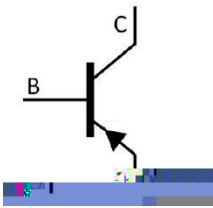


**/ Descriptions**

KF \$O) GE G` Silicon PNP transistor in a TO-92 Plastic Package.

) J: () (\* Žž  
Complementary pair with 2SC1213(A).

Low frequency power amplifier.



PIN1 Base      PIN 2 Collector      PIN 3 Emitter

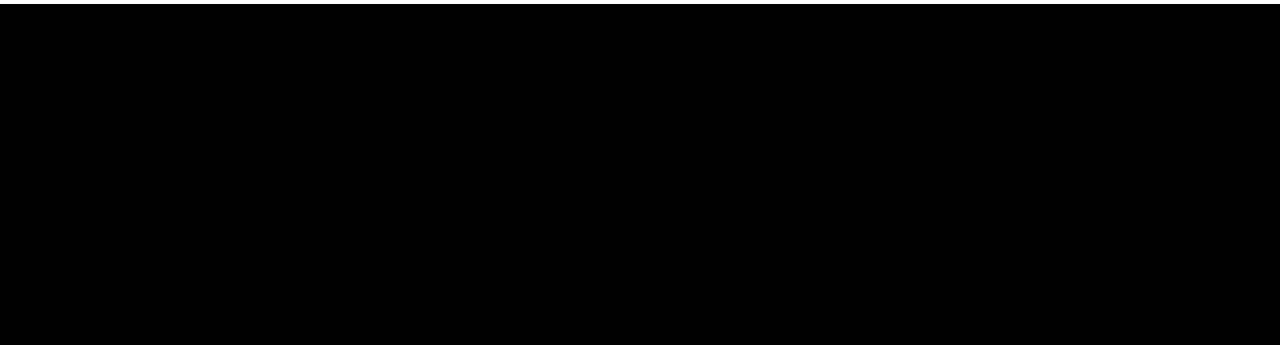
**/ hFE Classifications & Marking**

**/ Absolute Maximum Ratings(Ta=25 )**

Parameter	Symbol	Rating	Unit	
Collector to Base Voltage	V <sub>CBO</sub>	2SA673	-35	V
		2SA673A	-50	
Collector to Emitter Voltage	V <sub>CEO</sub>	2SA673	-35	V
		2SA673A	-50	
Emitter to Base Voltage	V <sub>EBO</sub>	-4.0	V	
Collector Current - Continuous	I <sub>C</sub>	-500	mA	
Collector Power Dissipation	P <sub>C</sub>	400	mW	
Junction Temperature	T <sub>j</sub>	150		
Storage Temperature Range	T <sub>stg</sub>	-55 150		

**/ Electrical Characteristics(Ta=25 )**

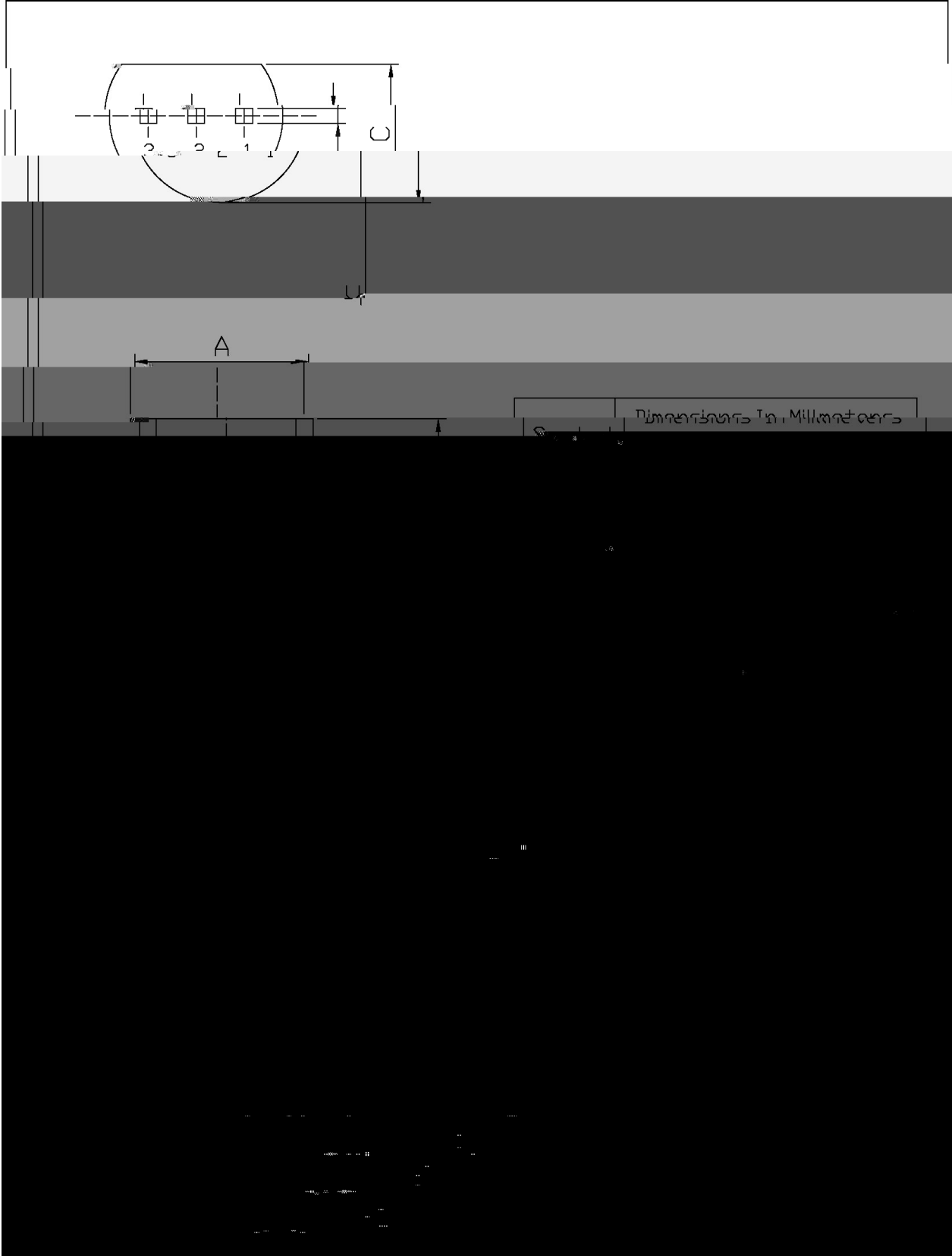
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V <sub>CBO</sub>	I <sub>C</sub> =-10 A I <sub>E</sub> =0	-35			V
			-50			
Collector to Emitter Breakdown Voltage	V <sub>CEO</sub>	I <sub>C</sub> =-1.0mA I <sub>B</sub> =0	-35			V
			-50			
Emitter to Base Breakdown Voltage	V <sub>EBO</sub>	I <sub>E</sub> =-10 A I <sub>C</sub> =0	-4.0			V
Collector Cut-Off Current	I <sub>CBO</sub>	V <sub>CB</sub> =-20V I <sub>E</sub> =0			-0.5	A
DC Current Gain	h <sub>FE(1)</sub>	V <sub>CE</sub> =-3.0V I <sub>C</sub> =-10mA	60		320	
	h <sub>FE(2)</sub>	V <sub>CE</sub> =-3.0V I <sub>C</sub> =-500mA	10			
Collector to Emitter Saturation Voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =-150mA I <sub>B</sub> =-15mA		-0.2	-0.6	V
Base to Emitter Voltage	V <sub>BE</sub>	V <sub>CE</sub> =-3.0V I <sub>C</sub> =-10mA		-0.64		V



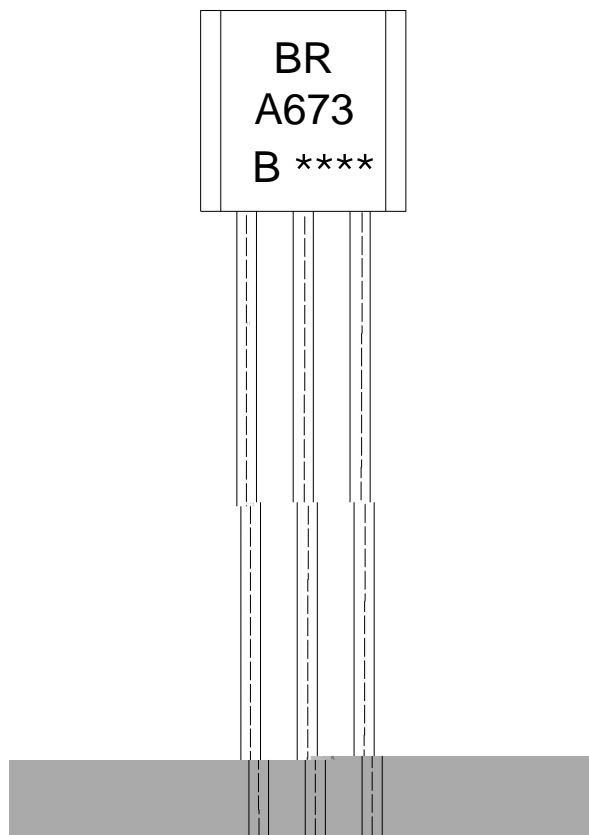
/ Package Dimensions

TO-92

Unit: mm



/ Marking Instructions



91 1  
8- . \*  
91  $h_{FE}$   
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Note:

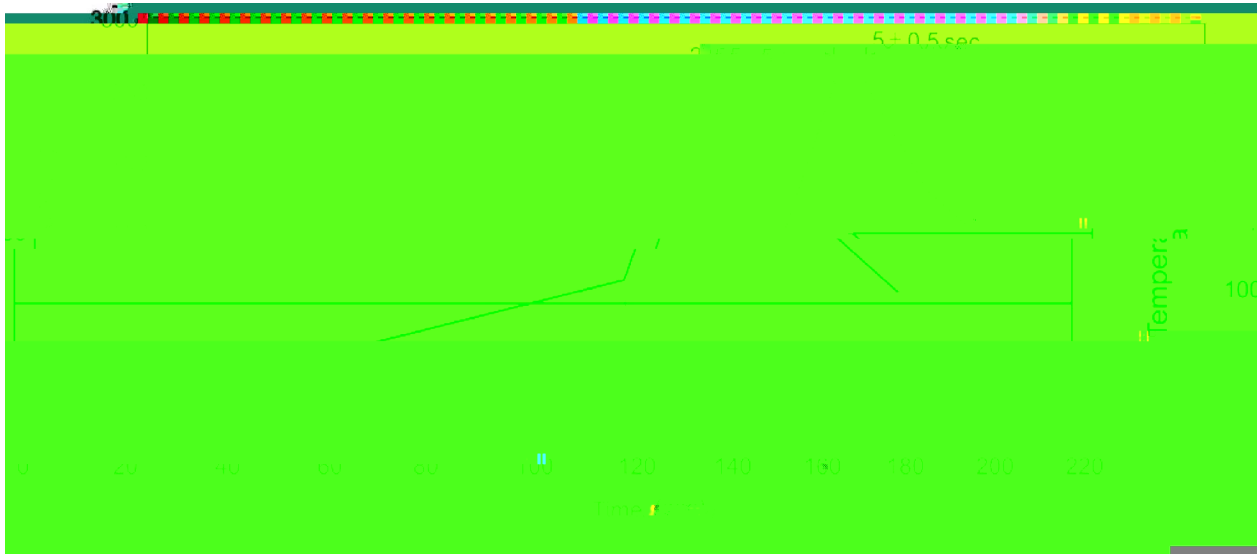
BR: Company Code.

A673: Product Type.

B:  $h_{FE}$  Classifications Symbol

\*\*\*\*: Lot No. Code,code change with Lot No.

( ) / Temperature Profile for Dip Soldering(Pb-Free)



- |   |        |     |            |        |       |   |
|---|--------|-----|------------|--------|-------|---|
| 1 | 25     | 150 | 60         | 90sec; | Note: | 1.Preheating:25~150 , Time:60~90sec.      |
| 2 | 255..5 |     | 5..0.5sec; |        |       | 2.Peak Temp.:255..5 , Duration:5..0.5sec. |
| 3 |        | 2   | 10         | /sec.  |       | 3. Cooling Speed: 2~10 /sec.              |

/ Resistance to Soldering Heat Test Conditions

270..5                      10..1 sec.                      Temp:270±5                      Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm3)		
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Bag 袋	Inner Box 盒	Outer Box 箱